

Method of Processing a Substrate

Abstract

The invention relates to a method of processing a substrate (W), having on one side (2) a device area (6) with a plurality of devices (8). The method comprises providing a first protective film (22), providing a second protective film (14), attaching the first protective film (22) to the one side (2) of the substrate (W), so that at least a central area of a front surface (24) of the first protective film (22) is in direct contact with the one side (2) of the substrate (W), and attaching the second protective film (14) to a side (4) of the substrate (W) being opposite to the one side (2). After attaching the second protective film (14) to the side (4) of the substrate (W) being opposite to the one side (2), a laser beam (LB) is applied to the substrate (W) from the side (4) of the substrate (W) being opposite to the one side (2). The substrate (W) is made of a material which is transparent to the laser beam (LB). The second protective film (14) is made of a material which is transparent to the laser beam (LB). The laser beam (LB) is applied to the substrate (W) in a plurality of positions so as to form a plurality of modified regions in the substrate (W).

[Figure 9]